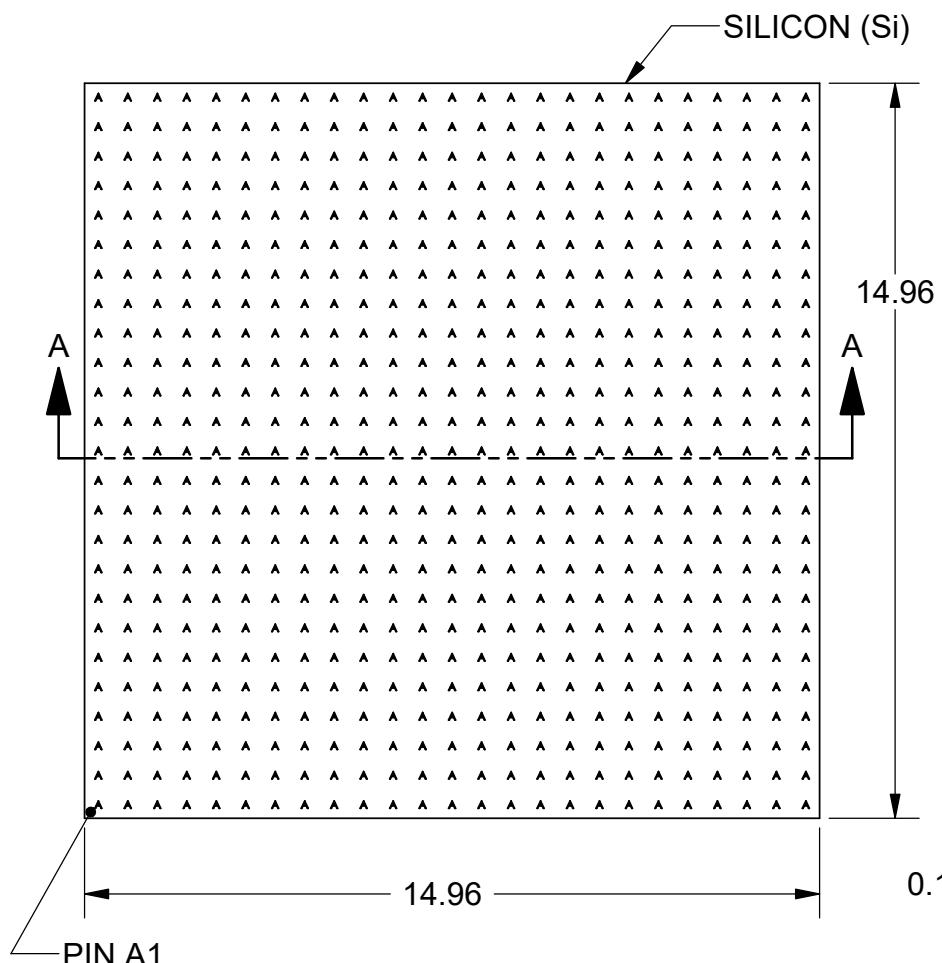
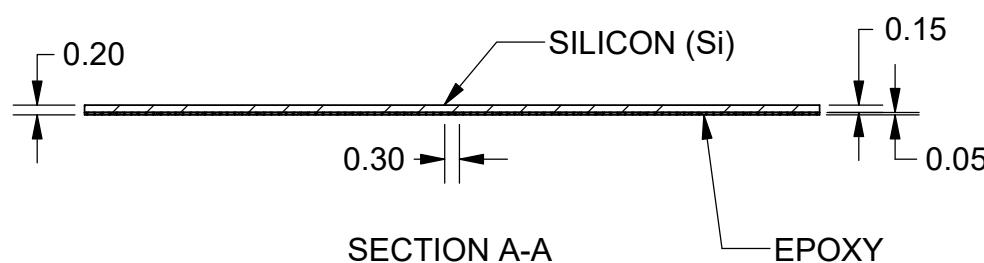
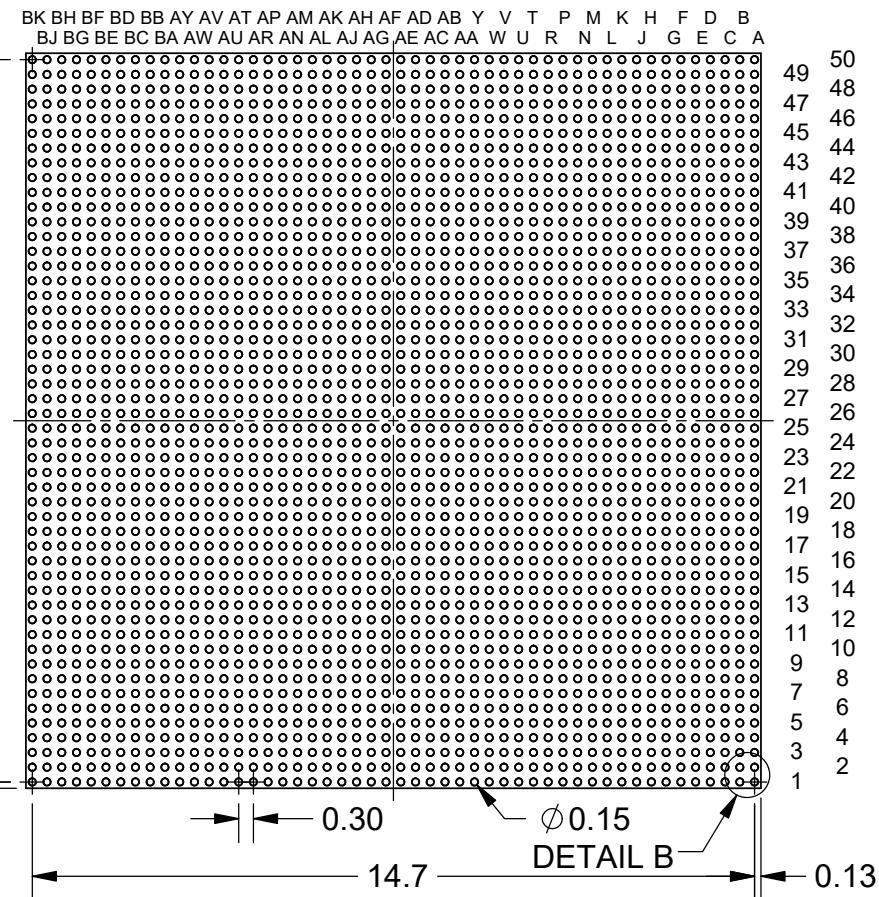


TOP VIEW



PAD VIEW



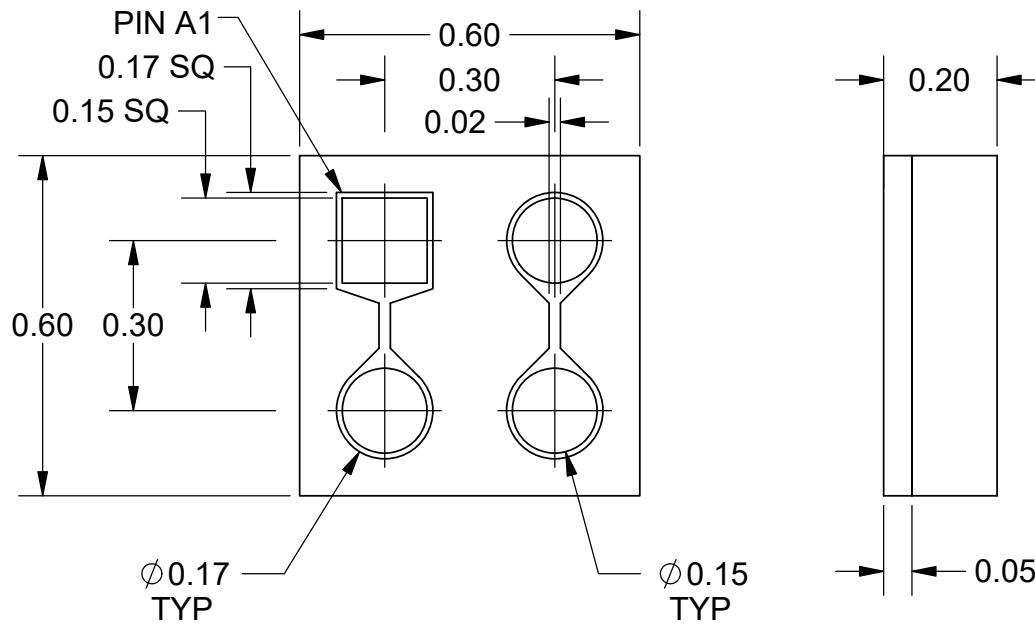
Notes: (Unless Otherwise Specified).

- 1) ALL DIMENSIONS ARE IN MM.
- 2) PAD ALLOY: Cu (50 μ m THICK).
- 3) PAD Cu DIAMETER 0.15mm.
- 4) SIE MATERIAL: Si (SILICON).
- 5) DAISY CHAIN PATTERN (SEE PAGE 3/4).

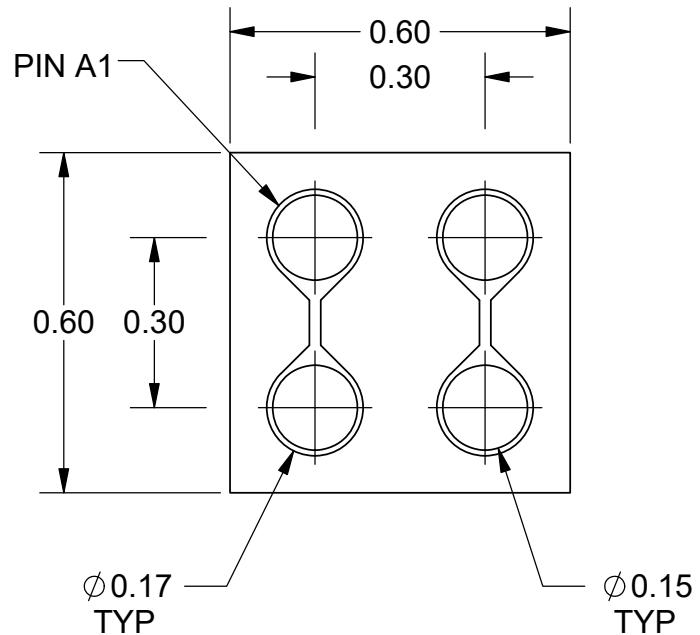
TOLERANCE UNLESS NOTED		APPROVALS	DATE	TopLine
X.X	+/- 0.1	DRAWN J. Hines	12/9/2016	
X.XX	+/- 0.05	ENG M. Hart	12/9/2016	TITLE eWLP2500T.3-DC508D
X.XXX	+/- 0.025	MFG		2500-L P=0.3mm (TEG0306)
ANGLES +/-. 0.5°		QA	SCALE 6.5:1	REV A
ALL DIMENSIONS IN □ INCHES <input checked="" type="checkbox"/> MILLIMETERS		CUST	SIZE A	DRAWING NO. 631480
THIRD ANGLE PROJECTION		REVISED	DO NOT SCALE DRAWING	
				SHEET 1 OF 6

DETAIL B
COPPER POST
SQUARE AND ROUND

OPTION SQ
SQUARE POST



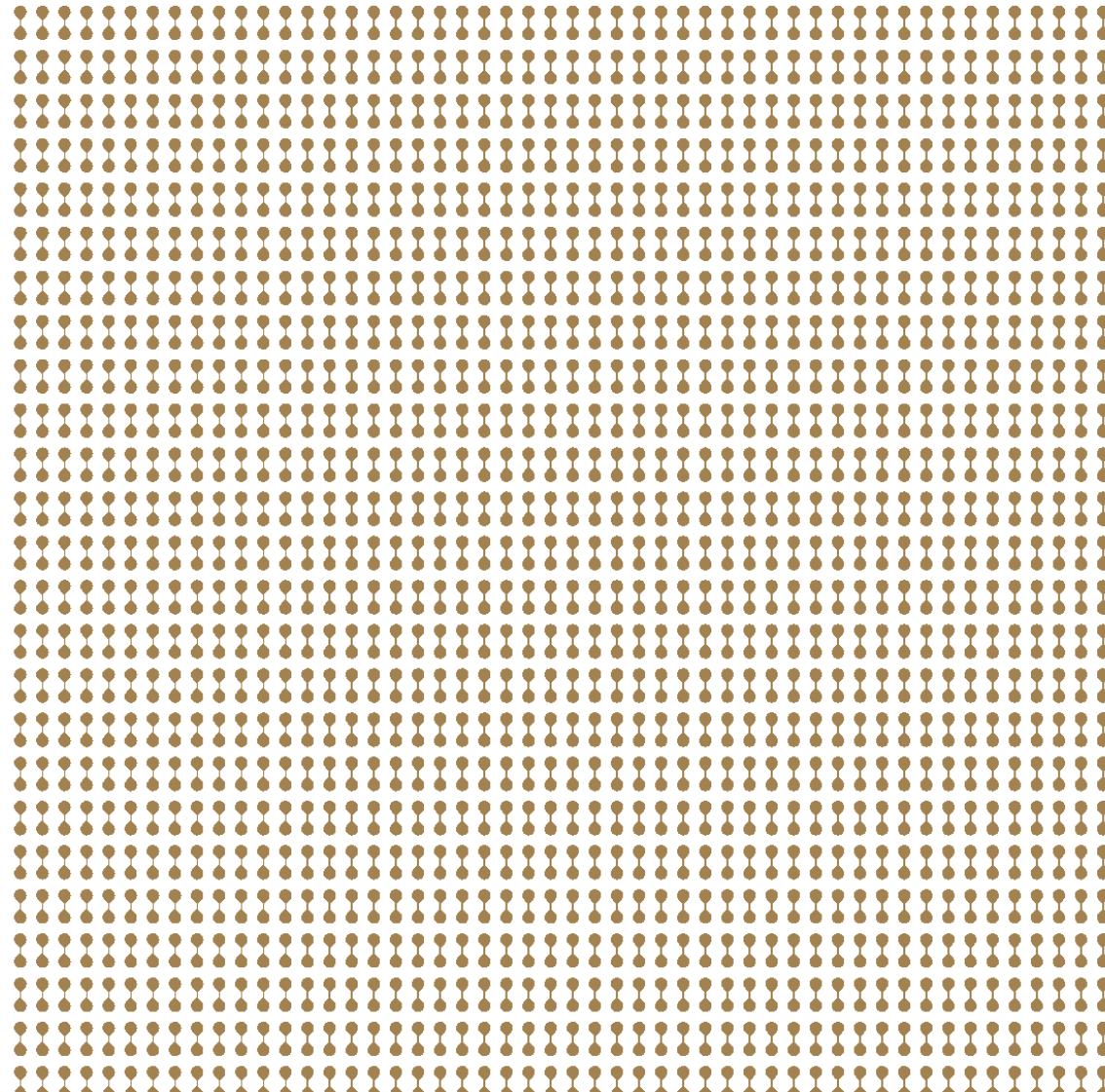
OPTION STANDARD
ROUND POST



TopLine			
TITLE eWLP2500T.3-DC508D 2500-L P=0.3mm (TEG0306)			
SCALE 75:1	SIZE A	DRAWING NO. 631480	REV A
DO NOT SCALE DRAWING			SHEET 2 OF 6

DAISY CHAIN PATTERN
PAD VIEW

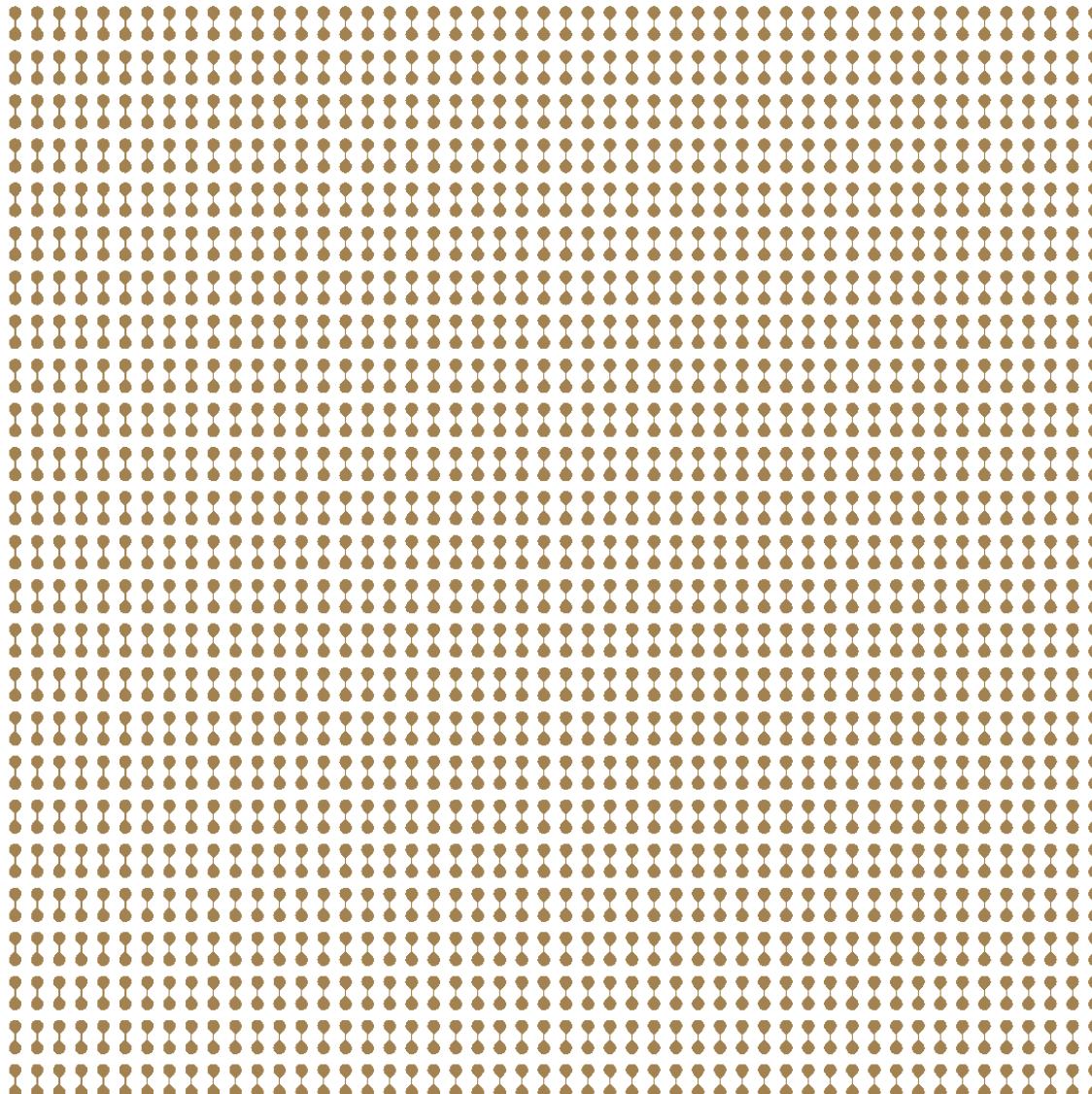
BK BH BF BD BB AY AV AT AP AM AK AH AF AD AB Y V T P M K H F D B
BJ BG BE BC BA AW AU AR AN AL AJ AG AE AC AA W U R N L J G E C A



TopLine			
TITLE eWLP2500T.3-DC508D 2500-L P=0.3mm (TEG0306)			
SCALE 10:1	SIZE A	DRAWING NO. 631480	REV A
DO NOT SCALE DRAWING		SHEET 3	OF 6

DAISY CHAIN PATTERN
TOP X-RAY VIEW OF PADS

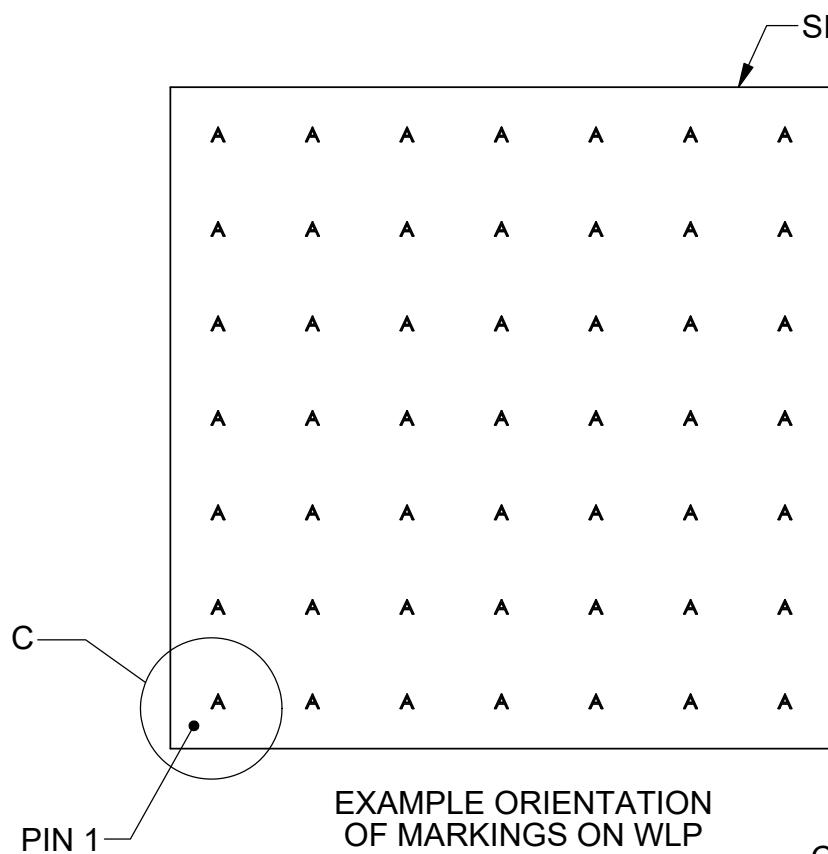
B D F H K M P T V Y AB AD AF AH AK AM AP AT AV AY BB BD BF BH BK
A C E G J L N R U W AA AC AE AG AJ AL AN AR AU AW BA BC BE BG BJ



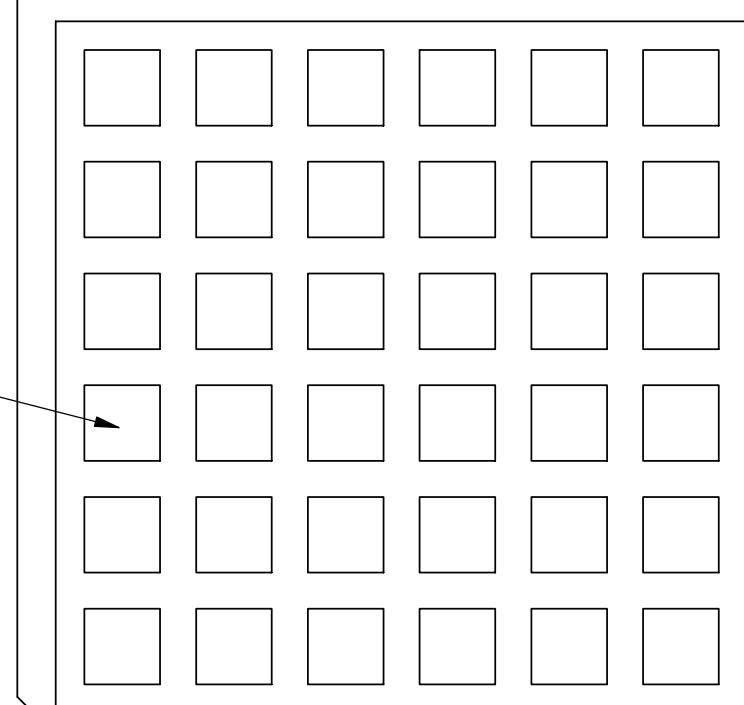
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TopLine			
TITLE eWLP2500T.3-DC508D 2500-L P=0.3mm (TEG0306)			
SCALE 10:1	SIZE A	DRAWING NO. 631480	REV A
DO NOT SCALE DRAWING			SHEET 4 OF 6

TOP VIEW

WLP ORIENTATION
WAFFLE PACKTYPICAL WAFFLE PACK
IC CHIP TRAY
SCALE = 2:1

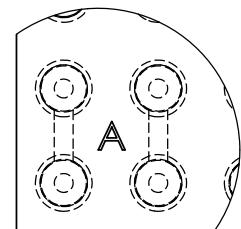
PIN 1 CHAMFER



NUMBER OF POCKETS WILL CHANGE BASED ON THE SIZE OF THE WLP CHIP

Notes: (Unless Otherwise Specified).

- 1) EXAMPLE OF TOP SIDE LASER MARKING.
- 2) ORIENT LETTERS FOR LOCATION OF PIN A1 CORNER.
- 3) ALLOWABLE LETTER MARKING: A, F, T, M, L, Y, AND P.
- 4) SINGLE LETTER IS REPEATED MULTIPLE TIMES ACROSS TOP SIDE.
- 5) DAISY CHAIN IS HIDDEN UNDER RESIN ON BALL SIZE.
- 6) TOP SIDE DOES NOT HAVE A DOT FOR LOCATION OF PIN A1.
- 7) LETTERS ARE NOT MARKED ON BOTTOM (BALL) SIDE.

DETAIL C
SCALE 25 : 1

MARKING CODE	
PITCH	LETTER
0.3MM	A
0.4MM	A OR F
0.5MM	A OR P

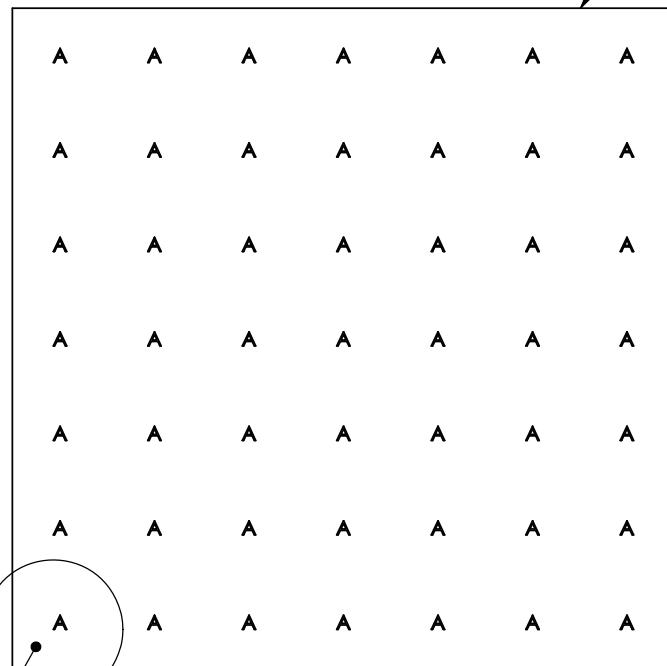
* SUBJECT TO CHANGE

TopLineTITLE eWLP2500T.3-DC508D
2500-L P=0.3mm (TEG0306)

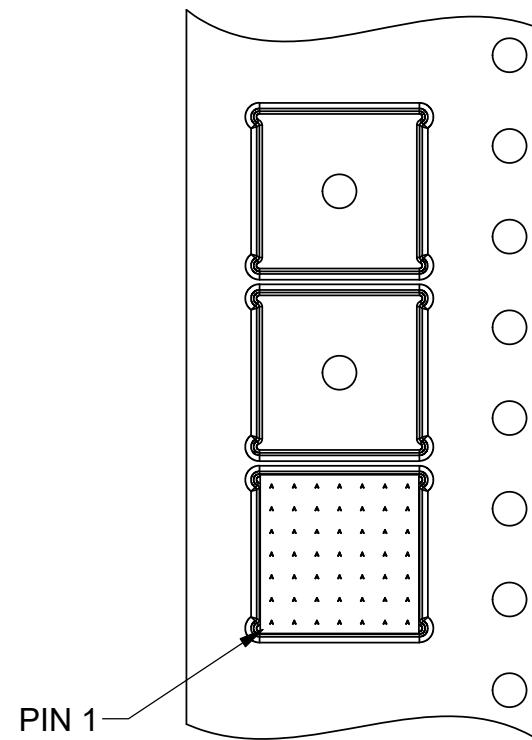
SCALE	SIZE	DRAWING NO.	REV
12.5:1	A	631480	A
DO NOT SCALE DRAWING			SHEET 5 OF 6

WLP ORIENTATION
TAPE AND REEL

TOP VIEW

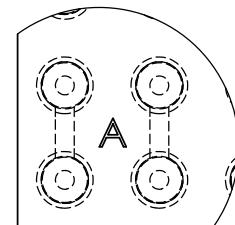


SILICON (Si)



PIN 1
D

EXAMPLE ORIENTATION
OF MARKINGS ON WLP



DAISY CHAIN
ORIENTATION
DETAIL D
SCALE 25 : 1

MARKING CODE	
PITCH	LETTER
0.3MM	A
0.4MM	A OR F
0.5MM	A OR P

* SUBJECT TO CHANGE

Notes: (Unless Otherwise Specified).

- 1) EXAMPLE OF TOP SIDE LASER MARKING.
- 2) ORIENT LETTERS FOR LOCATION OF PIN A1 CORNER.
- 3) ALLOWABLE LETTER MARKING: A, F, T, M, L, Y, AND P.
- 4) SINGLE LETTER IS REPEATED MULTIPLE TIMES ACROSS TOP SIDE.
- 5) DAISY CHAIN IS HIDDEN UNDER RESIN ON BALL SIZE.
- 6) TOP SIDE DOES NOT HAVE A DOT FOR LOCATION OF PIN A1.
- 7) LETTERS ARE NOT MARKED ON BOTTOM (BALL) SIDE.

TopLine			
TITLE eWLP2500T.3-DC508D			
2500-L P=0.3mm (TEG0306)			
SCALE 12.5:1	SIZE A	DRAWING NO. 631480	REV A
DO NOT SCALE DRAWING		SHEET 6 OF 6	